Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An electronic module comprising:

an electroluminescent section;

a first substrate on which the electroluminescent section is formed;

a second substrate attached to the first substrate;

an integrated circuit chip mounted on the second substrate; and

a plurality of power supply interconnects for allowing current to flow through the electroluminescent section,

~~wherein~~ the power supply interconnects ~~include:~~including: a plurality of first power supply interconnects formed on the first substrate, extending through a pair of regions located on both sides of the electroluminescent section; and a plurality of second power supply interconnects formed on the second substrate, extending through a pair of regions located on both sides of the integrated circuit chip, the first and second power supply interconnects being electrically connected.

2. (Currently Amended) The electronic module as defined by claim 1, further comprising:

a plurality of signal interconnects for inputting a drive signal from the integrated circuit chip to the electroluminescent section,

~~wherein~~ the signal interconnects ~~are~~being formed in a region ~~interposing~~interposed between a first region in which one part of the power supply interconnects are formed and a second region in which the other part of the power supply interconnects are formed.

3. (Currently Amended) The electronic module as defined by claim 2, ~~wherein~~a width of each of the signal interconnects ~~is~~being narrower than a width of each of the power supply interconnects.

4. (Currently Amended) The electronic module as defined by claim 2, further comprising:

a pair of scanning drivers disposed on both sides of the electroluminescent section, respectively, on the first substrate; and

a plurality of control interconnects for inputting a control signal from the integrated circuit chip to each of the scanning drivers,

~~wherein~~ the control interconnects ~~are~~being formed in a pair of regions which are located on both sides of a region in which the signal interconnects are formed and ~~interpose~~interposed between the first region and the second region.

5. (Currently Amended) The electronic module as defined by claim 1, further comprising:

a plurality of connector terminals formed on an end portion of the second substrate except a portion to which the first substrate is attached,

~~wherein~~a width of each of the connector terminals ~~is~~being formed to be wider than a width of each of the power supply interconnects.

6. (Original) An electronic instrument comprising the electronic module as defined by claim 1.

7. (Currently Amended) A method of manufacturing an electronic module comprising:

fixing a first substrate, on which an electroluminescent section is formed, with a second substrate on which an integrated circuit chip is mounted,

~~wherein~~ the first substrate ~~includes~~including a plurality of first power supply interconnects which are formed extending through a pair of regions located on both sides of the electroluminescent section,

~~wherein~~ the second substrate ~~includes~~including a plurality of second power supply interconnects which are formed extending through a pair of regions located on both sides of the integrated circuit chip, and

~~wherein~~ the first and second power supply interconnects ~~are~~being electrically connected in the step of fixing the first and second substrate.

8. (Original) An electronic module comprising:

an electronic substrate including a plurality of first terminals;

an interconnect substrate on which an interconnect pattern is formed, the interconnect pattern including a plurality of second terminals electrically connected with the first terminals of the electronic substrate, at least two first interconnects extending from at least two of the second terminals, and at least two second interconnects formed in a state to be electrically insulated from the first interconnects; and

an electrical connection section which electrically connects at least one of the first interconnects with at least one of the second interconnects.

9. (Currently Amended) The electronic module as defined by claim 8, further comprising:

an integrated circuit chip mounted on the interconnect substrate,

~~wherein~~ the second interconnects ~~are~~being electrically connected with the integrated circuit chip.

10. (Currently Amended) The electronic module as defined by claim 9,

~~wherein~~ the electrical connection section ~~is~~being provided at a position closer to the electronic substrate than the integrated circuit chip.

11. (Currently Amended) The electronic module as defined by claim 9,

~~wherein~~ the electrical connection section ~~is~~being provided in each of a pair of regions respectively located closer to both ends of the interconnect substrate than a center of the interconnect substrate in a widthwise direction.

12. (Original) An electronic instrument comprising the electronic module as defined by claim 8.

13. (Original) A method of manufacturing an electronic module comprising:

electrically connecting a plurality of first terminals of an electronic substrate with a plurality of second terminals of an interconnect substrate; and

electrically connecting at least one of two or more first interconnects extending from two or more of the second terminals with at least one of two or more second interconnects formed in a state to be electrically insulated from the first interconnects, by means of an electrical connection section.

14-23. (Canceled)